

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

## Title of Invention

OPTIMUM PADSET FOR WIRE BONDING RF  
TECHNOLOGIES WITH HIGH-Q INDUCTORS

Application Number :

Confirmation Number:

First Named Applicant: Douglas Coolbaugh

Attorney Docket Number: BUR920020119US1

Art Unit:

Examiner:

Search string: ( 4845543 or 5139192 or 5773899 or 5884835 or 6027999 or 6027999 or 6077766  
or 6218728 or 6306750 ).pn

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
B5	1	4845543	1989-07-04	Okikawa et al			
	2	5139192	1992-08-18	Simmonds			
	3	5773899	1998-06-30	Zambrano			
	4	5884835	1999-06-23	Kajiwarra et al			
	5	6027999	2000-02-22	Wong			
	6	6027999	2000-02-22	Wong			
	7	6077766	2000-06-20	Sebesta et al			
	8	6218728	2001-04-17	Kimura			
	9	6306750	2001-10-23	Huang et al			

## Signature

Examiner Name	Date
	9/14/05

**LIST OF PRIOR ART  
CITED BY APPLICANT**

(Use several sheets if necessary)



Atty. Docket N .  
BUR920020119US1 (16763)

Serial No.

Applicant  
Douglas D. Coolbaugh, et al

Filing Date

Group  
Unassigned

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL*		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	AA						
	AB						

**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		JP5-047859A	2/26/1993	JAPAN				

**OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

BS		S.G. Bombardier, et al. (1997) "Aluminum-Tungsten-Aluminum Sandwich for Semiconductor Chip Wirebond Pad", IBM Technical Disclosure Bulletin, Vol. 40, No. 6, page 131;
1		C.R. Fedorko, Jr., et al. (1984) "Packaging Substrate with Top Surface Metallurgy Adapted for Mixed Technology Device Bonding and Method", IBM Technical Disclosure Bulletin, Vol. 26, No. 12, page 6624;
		D. Chance, et al. (1993) "Thin Film Metallurgical Structure and Wire for Engineering Chance", IBM Technical Disclosure Bulletin, Vol. 36, No. 1, page 41;
		T.H. Chiles (1989) Abstract of Disclosure No. 30581 entitled "Use of a Composite Metal Pad for Wirebond connection to the Copper Core of a Metal Core Substrate Circuit Board" Kenneth Mason Publications, Ltd. England, No. 305 (1 page); and
✓		R. J. Bergeron, et al. (1992) Abstract of Disclosure No. 34237 entitled "Bond Pad Metallurgy for Wire Bonding", Kenneth Mason Publications, Ltd. England, No. 342 (1 page).

EXAMINER

*[Signature]*

DATE CONSIDERED

9/14/05

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.